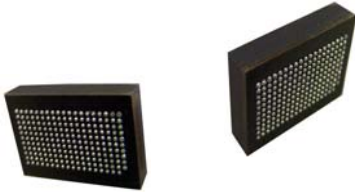
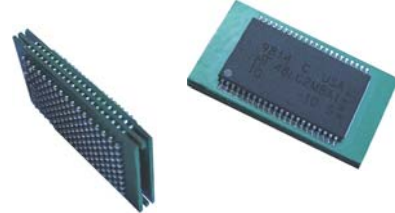


### Multi-Chip Packages (MCPs)

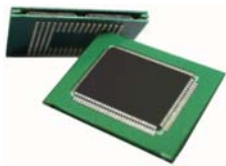
- ❖ 9-Chip Memory Module in a BGA Package



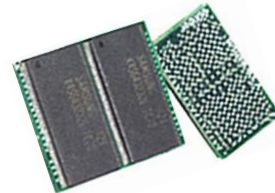
- ❖ SSD in a BGA Package



- ❖ Processor & Memory in a BGA Package



- ❖ SDRAM & Flash in a BGA Package



### Extended Temperature & Rugged Modules

- Extended Temperature Screening: -40C to +85C
- Thermal Heat Spreader & Heat Sink
- Conformal Coating
- Under-fill
- Thermal Sensor



### Slim & Rugged SSDs



### Industrial CompactFlash

- Extended Temperature: -40C to +85C
- Revision Control



### High Density Memory Modules

- ❖ Ultra Low Profile (ULP)



- ❖ Mezzanine Board



### Specialty Modules

- ❖ SSDDR™ : SSD & DDR SDRAM



- ❖ LeanSTOR™: SSD Card for AMC and  $\mu$ TCA



- ❖ SaveRAM™ : SDRAM & Flash Backup for RAID



- ❖ NAND DIMM

